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29. (NEW) An electronic structure, comprising:
bonding a mineral layer to a metallic plate; and
bonding an adhesion promoter layer to the mineral layer such that said bonding to the
mineral layer is moisture resistant.

Remarks

Prompt and favorable examination on the merits is respectfully requested. Applicant's
respectfully submit that the entire application is in condition for allowance. However, should the
Examiner believe anything further is necessary in order to place the application in better
condition for allowance, or if the Examiner believes that a telephone interview would be
advantageous to resolve the issues presented, the Examiner is invited to contact the Applicant's
undersigned representative at the telephone number listed below.

Respectfully submitted,

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Appendix A. Identification of Amended Material

Claims 11-16 and 18-19 are amended herein as follows.

11. (AMENDED) The method of claim 10, wherein [the step of] forming a mineral layer includes forming the mineral layer having [selecting] a mineral selected from the group consisting of silicon dioxide, silicon nitride, and silicon carbide.

12. (AMENDED) The method of claim 10, wherein [the step of] forming a mineral layer includes forming [a] the mineral layer having a thickness between about 50 angstroms and about 2000 angstroms.

13. (AMENDED) The method of claim 10, wherein [the step of] forming a mineral layer includes sputtering [a] the mineral layer on the clean surface of the metallic plate.

14. (AMENDED) The method of claim 10, wherein [the] providing [step] a metallic plate includes providing the metallic plate having [selecting] a metallic substance selected from the group consisting of stainless steel, aluminum, titanium, copper, copper coated with nickel, and copper coated with chrome.

15. (AMENDED) The method of claim 10, wherein [the step of] forming an adhesion promoter layer includes forming the adhesion promoter layer having [selecting] an adhesion promoter selected from the group consisting of [a silane,] a titanate, a zirconate, and an aluminate.

16. (AMENDED) The method of claim 10, wherein [the step of] forming an adhesion promoter layer includes forming the adhesion promoter layer [selecting] having a silane from the group consisting of 3-glycidoxypentyltrimethoxysilane, 3-glycidoxypentyltriethoxysilane, 3-(2-aminoethyl)pentyltrimethoxysilane, and 3-(2-aminoethyl)pentyltriethoxysilane.

18. (AMENDED) The method of claim 17, wherein [the step of] providing an adhesive material includes providing the adhesive material having a structural epoxy adhesive.

19. (AMENDED) The method of claim 17, wherein [the step of] providing a metallic plate includes providing [a] the metallic plate having a coefficient of thermal expansion (CTE) that exceeds a CTE of the electronic assembly.